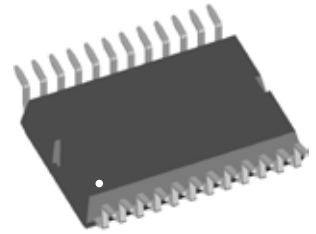
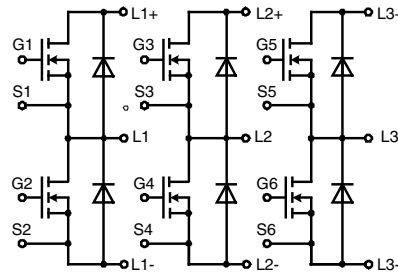


Three phase full Bridge with Trench MOSFETs in DCB isolated high current package

$$V_{DSS} = 100 \text{ V}$$

$$I_{D25} = 90 \text{ A}$$

$$R_{DSon \text{ typ.}} = 7.5 \text{ m}\Omega$$



MOSFETs

Symbol	Conditions	Maximum Ratings	
V_{DSS}	$T_{VJ} = 25^{\circ}\text{C to } 150^{\circ}\text{C}$	100	V
V_{GS}		± 20	V
I_{D25}	$T_C = 25^{\circ}\text{C}$	90	A
I_{D90}	$T_C = 90^{\circ}\text{C}$	68	A
I_{F25}	$T_C = 25^{\circ}\text{C (diode)}$	90	A
I_{F90}	$T_C = 90^{\circ}\text{C (diode)}$	68	A

Applications

- AC drives
 - in automobiles
 - electric power steering
 - starter generator
 - in industrial vehicles
 - propulsion drives
 - fork lift drives
- in battery supplied equipment

Features

- MOSFETs in trench technology:
 - low R_{DSon}
 - optimized intrinsic reverse diode
- package:
 - high level of integration
 - high current capability
 - aux. terminals for MOSFET control
 - terminals for soldering or welding connections
 - isolated DCB ceramic base plate with optimized heat transfer
- Space and weight savings

Symbol	Conditions	Characteristic Values ($T_{VJ} = 25^{\circ}\text{C}$, unless otherwise specified)			
		min.	typ.	max.	
$R_{DSon}^{1)}$	on chip level at $V_{GS} = 10 \text{ V}$				
	$T_{VJ} = 25^{\circ}\text{C}$		7.5	8.5	m Ω
	$T_{VJ} = 125^{\circ}\text{C}$		14		m Ω
$V_{GS(th)}$	$V_{DS} = 20 \text{ V}; I_D = 1 \text{ mA}$	2.5		4.5	V
I_{DSS}	$V_{DS} = V_{DSS}; V_{GS} = 0 \text{ V}$		0.1	1	μA
I_{GSS}	$V_{GS} = \pm 20 \text{ V}; V_{DS} = 0 \text{ V}$			0.2	μA
Q_g	$V_{GS} = 10 \text{ V}; V_{DS} = 65 \text{ V}; I_D = 90 \text{ A}$		90		nC
Q_{gs}			30		nC
Q_{gd}			30		nC
$t_{d(on)}$	inductive load $V_{GS} = 10 \text{ V}; V_{DS} = 48 \text{ V}$ $I_D = 70 \text{ A}; R_G = 33 \Omega;$ $T_J = 125^{\circ}\text{C}$		130		ns
t_r			95		ns
$t_{d(off)}$			290		ns
t_f			55		ns
E_{on}			0.4		mJ
E_{off}			0.4		mJ
E_{recoff}			0.007		mJ
R_{thJC}	with heat transfer paste (IXYS test setup)			1.0	K/W
R_{thJH}			1.3	1.6	K/W

¹⁾ $V_{DS} = I_D \cdot (R_{DS(on)} + 2R_{Pin \text{ to Chip}})$

Recommended replacement: MTI 85WX100GD

Source-Drain Diode

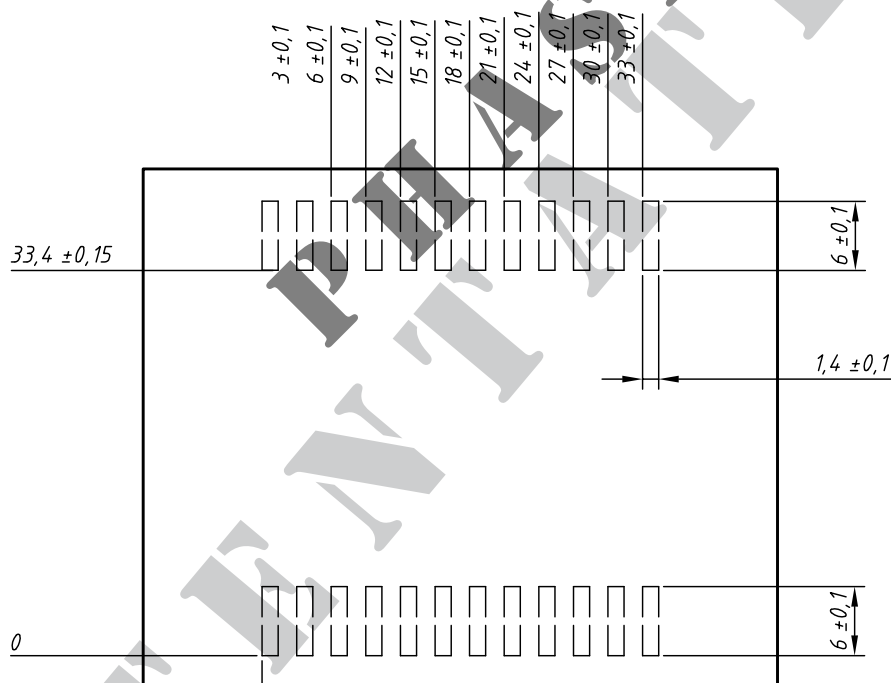
Symbol	Conditions	Characteristic Values			
		(T _J = 25°C, unless otherwise specified)			
		min.	typ.	max.	
V _{SD}	(diode) I _F = 70 A; V _{GS} = 0 V		0.9	1.2	V
t _{rr}	I _F = 70 A; -di _F /dt = 800 A/μs; V _R = 48 V		55		ns
Q _{RM}			0.95		μC
I _{RM}			33		A

Component

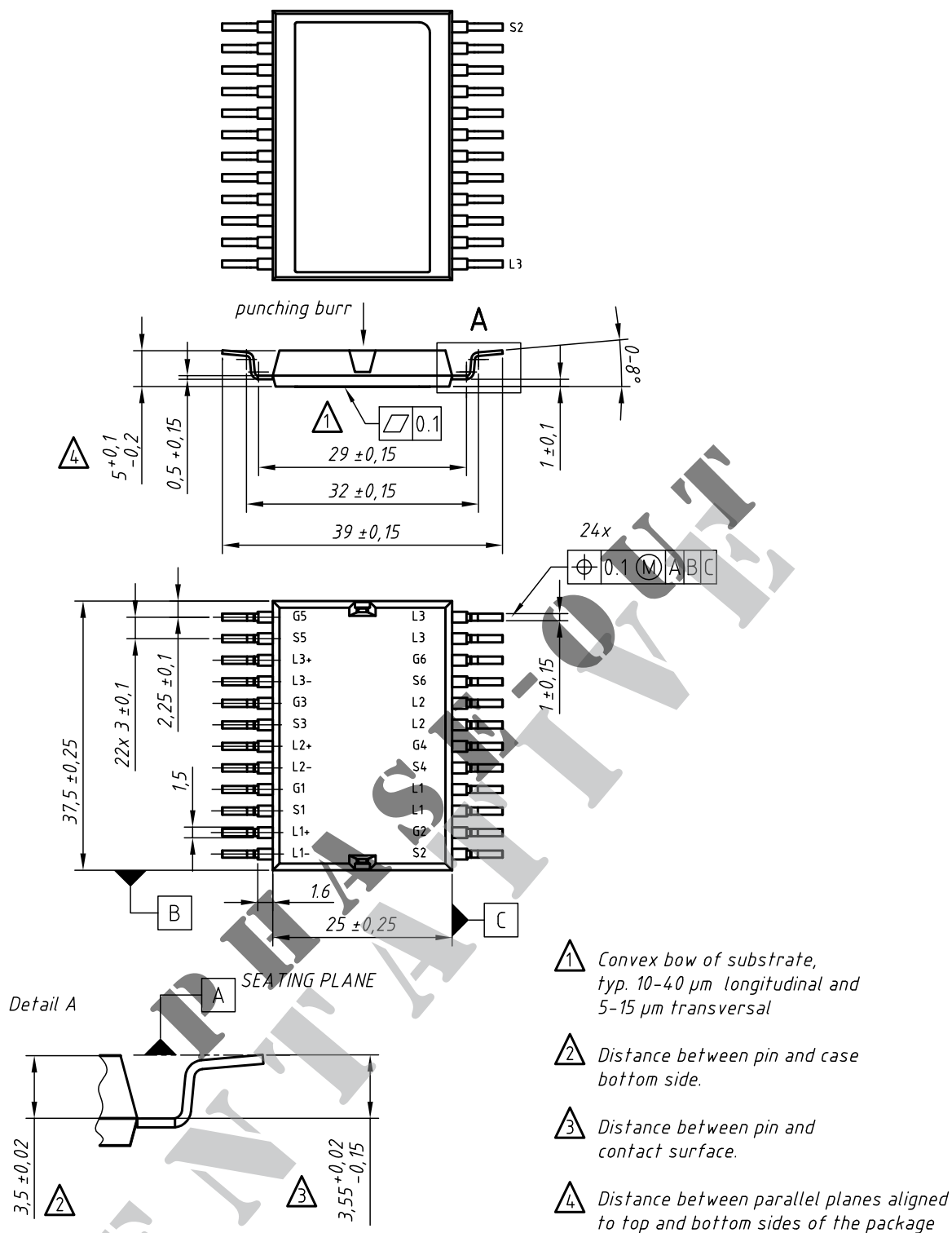
Symbol	Conditions	Maximum Ratings	
I _{RMS}	per pin in main current paths (P+, N-, L1, L2, L3) may be additionally limited by external connections 2 pins for output L1, L2, L3	75	A
T _J		-55...+175	°C
T _{stg}		-55...+125	°C
V _{ISOL}	I _{ISOL} ≤ 1 mA, 50/60 Hz, f = 1 minute	1000	V~
F _C	mounting force with clip	50 - 250	N

Symbol	Conditions	Characteristic Values		
		min.	typ.	max.
R _{pin to chip} ¹⁾			tbd	mΩ
C _P	coupling capacity between shorted pins and back side metallization		160	pF
Weight			25	g

¹⁾ V_{DS} = I_D · (R_{DS(on)} + 2R_{Pin to Chip})

Remarks:

- 1) pin layout / dimensions are conditionally
- 2) soldering paste thickness: 200μm



contact pin:

- galv. tin plating, per pin side: Sn 10...25 μm , undercoating Ni 0,2...1 μm
- stamping edges may be free of tin
- punching burr: $\leq 0,05 mm$

Leads	Ordering	Part Name & Packing Unit Marking	Part Marking	Delivering Mode	Base Qty.	Ordering Code
SMD	Standard	GMM 3x100-01X1 - SMD	GMM 3x100-01X1	Blister	28	509 035

IXYS reserves the right to change limits, test conditions and dimensions.

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